



Deposit No: 22562-7

PATENT

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Stephanie Berlepsch
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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Applicant: Kozo Saito et al.

Serial No.: 10/629,426

Group Art Unit: 2877

Filed: July 29, 2003

Examiner:

For: Systems and Methods for Inspecting Coatings

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In accordance with 37 C.F.R. §§ 1.97 and 1.98 Applicant herewith submits certain references which the Patent & Trademark Office may wish to consider in examining the above-identified application. The references are listed on the attached Form PTO-1449.

Copies of the cited publications are provided. Although copies of the cited U.S. patents are not required to be filed, please contact the undersigned if copies of any of the patents are needed. No representation is made or intended that a prior art search has been made or that no better art than that listed is available.

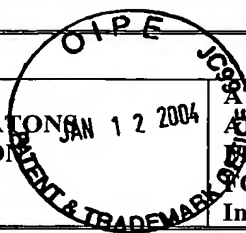
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Respectfully submitted,

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FORM PTO - 1449

LIST OF PATENTS AND PUBLICATIONS
FOR APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

ATTY DOCKET: 22562-7

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GROUP:

UNITED STATES LETTERS PATENT

Exr. Init.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
	3 0 2 0 7 4 5	Feb. 13, 1962	Sielicki		
	4 6 3 3 5 9 4	Jan. 6, 1987	Bovone		
	4 6 3 4 2 9 1	Jan. 6, 1987	Bantel et al.		
	4 9 9 6 4 2 6	Feb. 26, 1991	Cielo et al.		
	5 0 7 5 5 5 2	Dec. 24, 1991	McClelland et al.		
	5 1 1 1 0 4 8	May 5, 1992	Devitt et al.		
	5 2 9 4 1 9 8	Mar. 15, 1994	Schlagheck		
	5 3 5 8 3 3 3	Oct. 25, 1994	Schmidt et al.		
	5 3 7 6 7 9 3	Dec. 27, 1994	Lesniak		
	5 8 0 8 3 0 3	Sep. 15, 1998	Schlagheck et al.		
	6 0 0 0 8 4 4	Dec. 14, 1999	Cramer et al.		
	6 2 7 1 8 7 8	Aug. 7, 2001	Sera		
	6 3 3 9 3 3 7	Jan. 15, 2002	Matsuda et al.		
	6 3 4 6 7 0 4	Feb. 12, 2002	Kenway		
	6 3 9 9 9 4 9	Jun. 4, 2002	Roney, Jr. et al.		
	6 4 0 0 1 2 8	Jun. 4, 2002	Guidotti et al.		
	6 4 0 8 9 1 7	Jun. 25, 2002	Bett et al.		
	6 4 5 2 1 8 0	Sep. 17, 2002	Nistler et al.		
	6 4 6 1 0 3 5	Oct. 8, 2002	Meinlschmidt et al.		
	6 4 9 1 4 2 6	Dec. 10, 2002	Schonath et al.		
	6 5 1 5 2 8 4	Feb. 4, 2003	Walle et al.		
	6 5 1 7 2 3 8	Feb. 11, 2003	Sun et al.		

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS
62 1 9 8 7 0 7	02.09.87	JP		
02 0 2 2 5 4 7	25.01.90	JP		

OTHER ART (INCLUDING AUTHOR, TITLE DATE, PERTINENT PAGES, ETC.)

Feeler, Robert A., "Infrared Thermography Offers New Possibilities for Nondestructive Testing," Flight Safety Foundation, Aviation Mechanics Bulletin, May-June 1995
Shubinsky, Gary, "Visual & Infrared Imaging for Bridge Inspection," Northwestern University BIRL Basic Industrial Research Laboratory, June 1994
"Heat Conduction in Solids with Buried Discontinuities," Nondestructive Testing Handbook, Infrared and Thermal Testing, Third Edition, Vol. 3, pg. 62
Favro, L.D., Xiaoyan Han, P.K. Kuo and R.L. Thomas, "Measuring Defect Depths by Thermal-Wave Imaging," Thermosense XVIII: An International Conference on Thermal Sensing and Imaging Diagnostic Applications, Vol. 2766, pp. 236-239, March 1996
Maldague, Xavier P.V., "Theory and Practice of Infrared Technology for Nondestructive Testing," May 2001

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and no considered. Include copy of this form with next communication to applicant.